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763 U.S.P.T.O.  
**UTILITY PATENT APPLICATION TRANSMITTAL**Docket No.  
24295/81003

(Only for new non provisional applications under 37 CFR 1.53(b))

Total Pages in this Submission  
70**TO THE COMMISSIONER FOR PATENTS**

Mail Stop Patent Application  
P.O. Box 1450  
Alexandria, CA 22313-1450

Transmitted herewith for filing under 35 U.S.C. 111(a) and 37 C.F.R. 1.53(b) is a new utility patent application for an invention entitled:

Chip Testing Within A Multi-Chip Semiconductor Package

and invented by:

Adrian E. Ong

If a **CONTINUATION APPLICATION**, check appropriate box and supply the requisite information:

Continuation     Divisional     Continuation-in-part (CIP)    of a prior application No.: 09/666,208

Which is a:

Continuation     Divisional     Continuation-in-part (CIP)    of a prior application No.: \_\_\_\_\_

Which is a:

Continuation     Divisional     Continuation-in-part (CIP)    of a prior application No.: \_\_\_\_\_

Enclosed are:

**Application Elements**

1.  Filing fee as calculated and transmitted as described below
2.  Specification having 35 pages and including the following:
  - a.  Descriptive Title of the Invention
  - b.  Cross References to Related Applications (if applicable)
  - c.  Statement Regarding Federally-sponsored Research/Development (if applicable)
  - d.  Technical Field of Invention
  - e.  Background of the Invention
  - f.  Description of Related Art
  - g.  Brief Summary of the Invention
  - h.  Brief Description of the Drawings (if filed)
  - i.  Detailed Description
  - j.  Claims as Classified Below
  - k.  Abstract of the Disclosure

2253 U.S.P.T.O.  
10/824734

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## Application Elements (continued)

3.  Drawing(s) (when necessary as prescribed by 35 USC 113)
  - a.  Formal Number of Sheets \_\_\_\_\_
  - b.  Informal Number of Sheets nine (9)
4.  Oath or Declaration
  - a.  Newly executed (*original or copy*)  Unexecuted
  - b.  Copy from a prior application (37 CFR 1.63(d)) (*for continuation/divisional application only*)
  - c.  With Power of Attorney  Without Power of Attorney
  - d.  DELETION OF INVENTOR(S)  
Signed statement attached deleting inventor(s) named in the prior application, see 37 C.F.R. 1.63(d)(2) and 1.33(b).
5.  Incorporation By Reference (*usable if Box 4b is checked*) The entire disclosure of the prior application, from which a copy of the oath or declaration is supplied under Box 4b, is considered as being part of the disclosure of the accompanying application and is hereby incorporated by reference therein.
6.  CR ROM or CD-R in duplicate, large table or Computer Program (Appendix)
7.  Application Data Sheet (See 37 CFR 1.76)
8.  Nucleotide and/or Amino Acid Sequence Submission (*if applicable, all must be included*)
  - a.  Computer Readable Form (CRF)
  - b.  Specification Sequence Listing on:
    - i.  CD-ROM or CD-R (2 copies); or
    - ii.  Paper
  - c.  Statement(s) Verifying Identical Paper and Computer Readable Copy

## Accompanying Application Parts

9.  Assignment Papers (*cover sheet & documents(s)- copy from parent*)
10.  37 CFR 3.73(B) Statement (*when there is an assignee*)
11.  English Translation Document (*if applicable*)
12.  Information Disclosure Statement/PTO-1449  Copes of Disclosure Statement, PTO-1449 form, and PTO-892 form (*copy from parent*)
13.  Preliminary Amendment
14.  Return Receipt Postcard (MPEP 503) (*Should be specifically itemized*)
15.  Certified Copy of Priority Document(s) (*if foreign priority is claimed*)
16.  Certificate of Mailing

First Class  Express Mail (Specify Label No.): EV 305 258 523 US

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## Accompanying Application Parts (Continued)

17.  Additional Enclosures (please identify below):

Notice of Change of Address.

## Request That Application Not Be Published To 35 U.S.C. 122(b)(2)

18.  Pursuant to 35 U.S.C. 122(b)(2), Applicant hereby requests that this patent application not be published pursuant to 35 U.S.C. 122(b)(1). Applicant hereby certifies that the invention disclosed in this application has not and will not be subject of an application filed in another country, or under a multilateral international agreement, that requires publication of applications 18 Months after filing of the application.

### Warning

*An applicant who makes a request not to publish, but who subsequently files in a foreign country or under a multilateral international agreement specified in 35 U.S.C. 122(b)(2)(B)(i), must notify the Director of such filing not later than 45 days after the date of the filing of such foreign or international application. A failure of the applicant to provide such notice within the prescribed period shall result in the application being regarded as abandoned, unless it is shown to the satisfaction of the Director that the delay in submitting the notice was unintentional.*

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## Fee Calculation and Transmittal

### CLAIMS AS FILED

For	# Filed	# Allowed	# Extra	Rate	Fee
Total Claims	25	- 20 =	5	x \$9.00	\$45.00
Indep. Claims	4	- 3 =	1	x \$43.00	\$43.00
Multiple Dependent Claims (check if applicable)		<input type="checkbox"/>			\$0.00
				<b>BASIC FEE</b>	<b>\$385.00</b>
OTHER FEE (specify purpose)					\$0.00
				<b>TOTAL FILING FEE</b>	<b>\$ 473.00</b>

A check in the amount of \_\_\_\_\_ to cover the filing fee is enclosed.

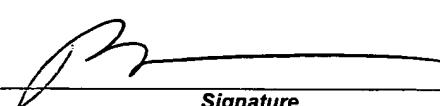
The director is hereby authorized to charge and credit Deposit Account No. 50-1597 as described below.

Charge the amount of \$473.00 as filing fee.

Credit any overpayment.

Charge any additional filing fees required under 37 C.F.R. 1.16 and 1.17.

Charge the issue fee set in 37 C.F.R. 1.18 at the mailing address of the Notice of Allowance, pursuant to 37 C.F.R. 1.311(b).



Signature

Philip W. Woo  
Attorney of Record  
Reg. No. 39,880

Dated: April 15, 2004

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Adrian E. Ong  
Assignee: Inapac Technology, Inc.  
Title: Chip Testing Within A Multi-Chip Semiconductor Package  
Application No.: 09/666,208 Filing Date: September 21, 2000  
Examiner: Unknown Group Art Unit: 2814  
Docket No.: M-8705 US Confirmation No.: Unknown

San Francisco, California  
February 24, 2003

COMMISSIONER FOR PATENTS  
Washington, D. C. 20231

**NOTICE OF CHANGE OF ADDRESS**

Dear Sir:

Please direct all correspondence in the above-identified application and with respect to any patent that issues on this application to the undersigned at this address:

Philip W. Woo  
c/o SIDLEY AUSTIN BROWN & WOOD LLP  
555 CALIFORNIA STREET  
SUITE 5000  
SAN FRANCISCO, CA 94104-1715  
TEL. (415) 772-1200  
FAX (415) 397-4621

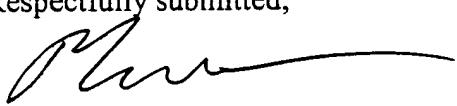
Certificate of Mailing

I hereby certify that this correspondence is being deposited with the United States Postal Service on the date shown below with sufficient postage as first class mail in an envelope addressed to: Commissioner for Patents, Washington, D.C. 20231.

2/24/03

Richard A. Pask

Respectfully submitted,

  
Philip W. Woo  
Attorney of Record  
Reg. No. 39,880

Date

Richard A. Pask